

Docket: CS 99 - 065
S/N: 09/442,499



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GP 1763

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

From: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 09/442,499
Inventor: Ho

Filed: 11/18/99

Title: Plasma Etch Method For Forming Plasma Etched Silicon Layer

Group Art Unit: 1763
Attorney Docket: CS 99 - 065

Examiner: Goudreau, G. A.

RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

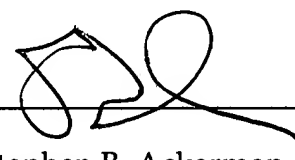
In response to the Final office action dated 05/20/03, please
consider the following remarks:

#18 E
6/24/03
mw

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the
United States Postal Service as first class mail in an envelope addressed to:
Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on ____
June 18, 2003.

Signature/Date


Stephen B. Ackerman

6/18/03

Reg. No. 37,761